# ne<mark>x</mark>peria

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Kind regards,

Team Nexperia

# INTEGRATED CIRCUITS



Product specification

IC24 Data Handbook

1995 Sep 18



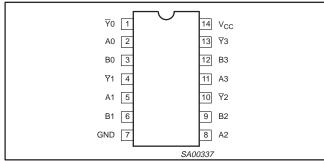
Philips Semiconductors

### 74ABT02

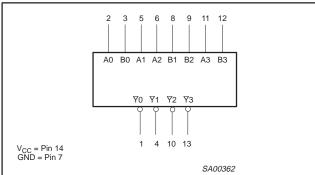
### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T <sub>amb</sub> = 25°C; GND = 0V	TYPICAL	UNIT
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay An or Bn to Ƴn	C <sub>L</sub> = 50pF; V <sub>CC</sub> = 5V	2.4 1.8	ns
t <sub>OSLH</sub> t <sub>OSHL</sub>	Output to Output skew		0.4	ns
C <sub>IN</sub>	Input capacitance	$V_{I} = 0V \text{ or } V_{CC}$	3	pF
Icc	Total supply current	Outputs disabled; $V_{CC} = 5.5V$	50	μA

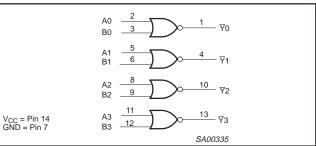
### **PIN CONFIGURATION**



### LOGIC SYMBOL



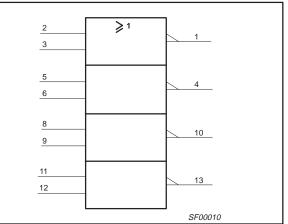
### LOGIC DIAGRAM



### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION
2, 3, 5, 6, 8, 9, 11, 12	An-Bn	Data inputs
1, 4, 10, 13	₹	Data outputs
7	GND	Ground (0V)
14	V <sub>CC</sub>	Positive supply voltage

### LOGIC SYMBOL (IEEE/IEC)



### **FUNCTION TABLE**

INP	JTS	OUTPUT
An	Bn	Ϋ́n
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

NOTES:

H = High voltage level L = Low voltage level

#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic DIP	-40°C to +85°C	74ABT02 N	74ABT02 N	SOT27-1
14-Pin plastic SO	-40°C to +85°C	74ABT02 D	74ABT02 D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT02 DB	74ABT02 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT02 PW	74ABT02PW DH	SOT402-1

### 74ABT02

#### **ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>**

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>1</sub> < 0	-18	mA
VI	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	-50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	-0.5 to +5.5	V
I <sub>OUT</sub>	DC output current	output in Low state	40	mA
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction

temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIM	UNIT	
		MIN	MAX	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-15	mA
I <sub>OL</sub>	Low-level output current		20	mA
Δt/Δv	Input transition rise or fall rate	0	5	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

### **DC ELECTRICAL CHARACTERISTICS**

SYMBOL	PARAMETER	TEST CONDITIONS		T <sub>amb</sub> = +25°C			T <sub>amb</sub> = −40°C to +85°C	
			MIN	TYP	MAX	MIN	MAX	
V <sub>IK</sub>	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V
V <sub>OH</sub>	High-level output voltage	$V_{CC}$ = 4.5V; $I_{OH}$ = -15mA; $V_I$ = $V_{IL}$ or $V_{IH}$	2.5	2.9		2.5		V
V <sub>OL</sub>	Low-level output voltage	$V_{CC}$ = 4.5V; $I_{OL}$ = 20mA; $V_I$ = $V_{IL}$ or $V_{IH}$		0.35	0.5		0.5	V
l <sub>l</sub>	Input leakage current	$V_{CC} = 5.5V; V_{I} = GND \text{ or } 5.5V$		±0.01	±1.0		±1.0	μΑ
I <sub>OFF</sub>	Power-off leakage current	$V_{CC}$ = 0.0V; $V_O$ or $V_I \le 4.5V$		±5.0	±100		±100	μA
I <sub>CEX</sub>	Output High leakage current	$V_{CC}$ = 5.5V; $V_{O}$ = 5.5V; $V_{I}$ = GND or $V_{CC}$		5.0	50		50	μA
Ι <sub>Ο</sub>	Output current <sup>1</sup>	$V_{CC} = 5.5$ V; $V_{O} = 2.5$ V	-50	-75	-180	-50	-180	mA
I <sub>CC</sub>	Quiescent supply current	$V_{CC} = 5.5$ V; $V_I = GND$ or $V_{CC}$		2	50		50	μΑ
$\Delta I_{CC}$	Additional supply current per input pin <sup>2</sup>	$V_{CC}$ = 5.5V; One data input at 3.4V, other inputs at $V_{CC}$ or GND		0.25	500		500	μΑ

#### NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

2. This is the increase in supply current for each input at 3.4V.

74ABT02

### **AC CHARACTERISTICS**

GND = 0V;  $t_R = t_F = 2.5$ ns;  $C_L = 50$ pF,  $R_L = 500\Omega$ 

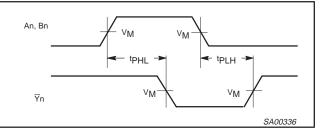
					LIMI	ſS		
SYMBOL	PARAMETER	WAVEFORM	T <sub>a</sub> V	<sub>amb</sub> = +25° ′ <sub>CC</sub> = +5.0′	C V	T <sub>amb</sub> = −40°C to +85°C V <sub>CC</sub> = +5.0V ±0.5V		UNIT
			MIN	ТҮР	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay An or Bn to Yn	1	1.0 1.0	2.4 1.8	3.7 2.8	1.0 1.0	4.4 3.4	ns
<sup>t</sup> OSHL t <sub>OSLH</sub> 1	Output to Output skew An or Bn to Yn	2		0.4 0.4	0.5 0.5		0.5 0.5	ns

NOTE:

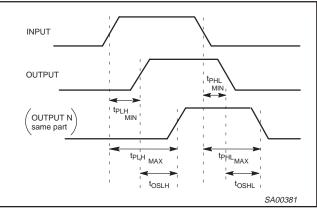
 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

### AC WAVEFORMS

 $V_{M} = 1.5V, V_{IN} = GND \text{ to } 3.0V$ 

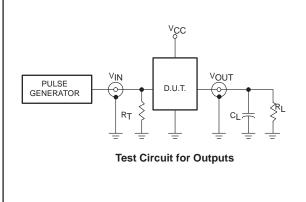


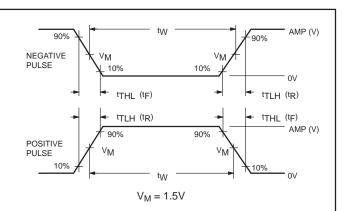
Waveform 1. Propagation delay for inverting outputs



Waveform 2. Common edge skew

### TEST CIRCUIT AND WAVEFORMS





#### Input Pulse Definition

### DEFINITIONS

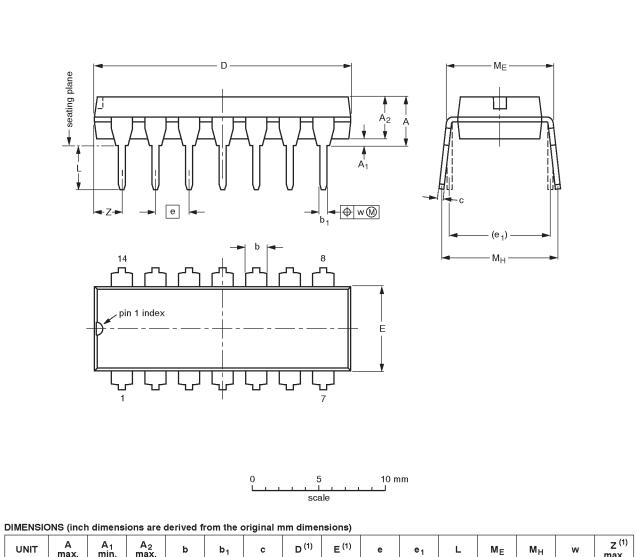
- R<sub>L</sub> = Load resistor; see AC CHARACTERISTICS for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.
- $\label{eq:RT} R_T = \begin{tabular}{ll} Termination resistance should be equal to $Z_{OUT}$ of pulse generators. \end{tabular}$

FAMILY	IN	PUT PULSE R	EQUIRE	MENTS	
	Amplitude	Rep. Rate	t <sub>W</sub>	t <sub>R</sub>	t <sub>F</sub>
74ABT	3.0V	1MHz	500ns	2.5ns	2.5ns
					SHOODEZ

#### 1995 Sep 18

# Quad 2-input NOR gate

DIP14: plastic dual in-line package; 14 leads (300 mil)



UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	ME	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES				
VERSION	IEC	JEDEC	EIAJ			ISSUE DATE	
SOT27-1	050G04	MO-001AA				<del>-92-11-17</del> 95-03-11	

# 74ABT02

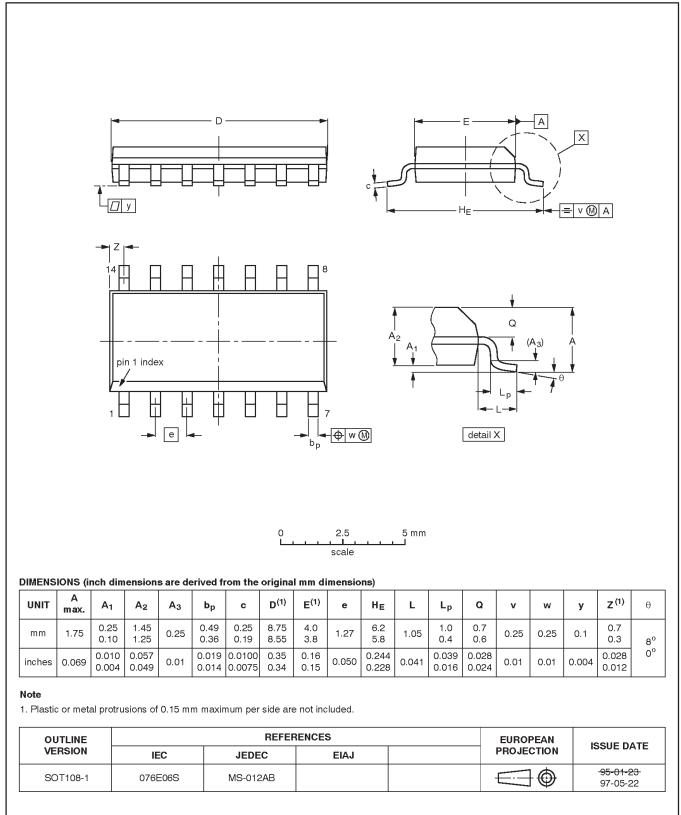
SOT27-1

Product specification

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SOT108-1

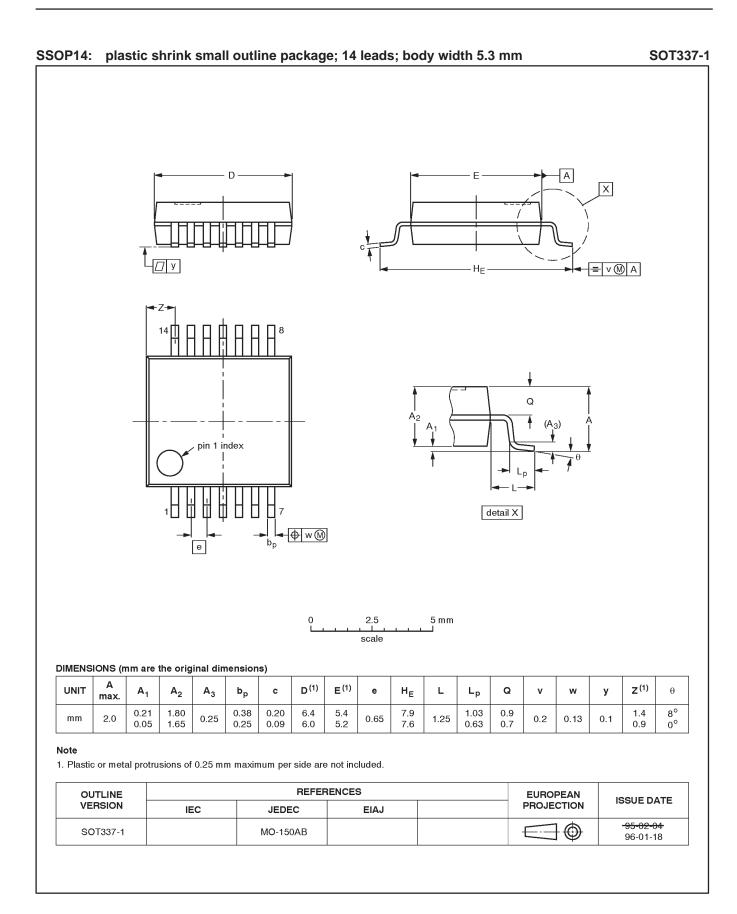
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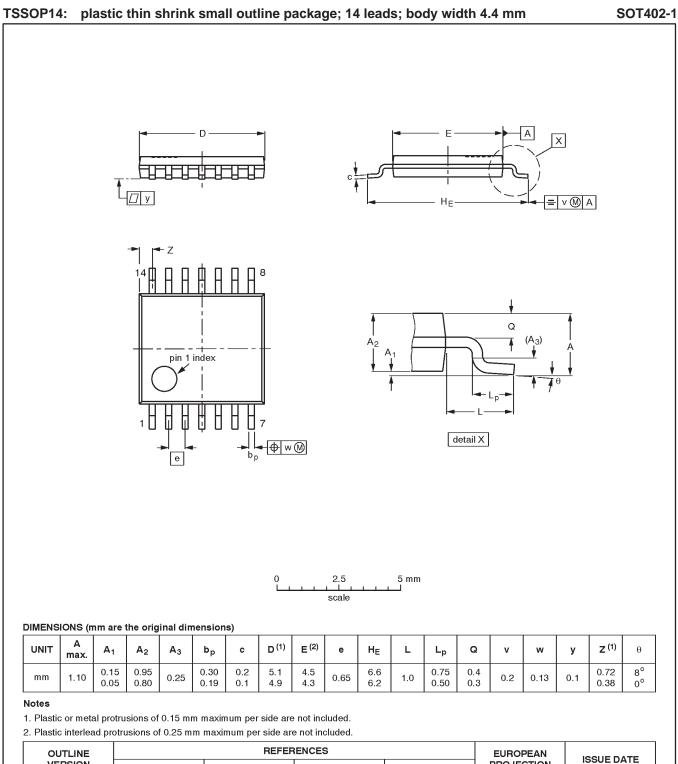
### SO14: plastic small outline package; 14 leads; body width 3.9 mm

#### 1995 Sep 18

### 74ABT02



### 74ABT02



74ABT02

NOTES

### 74ABT02

DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
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